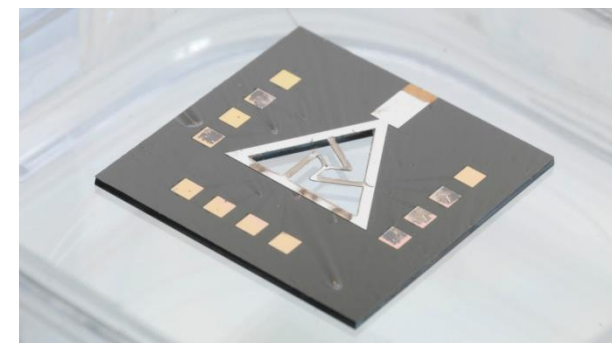
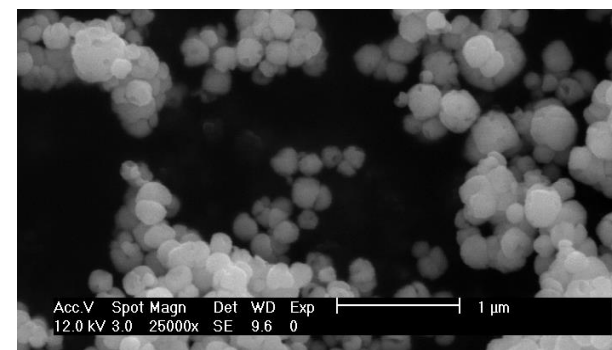
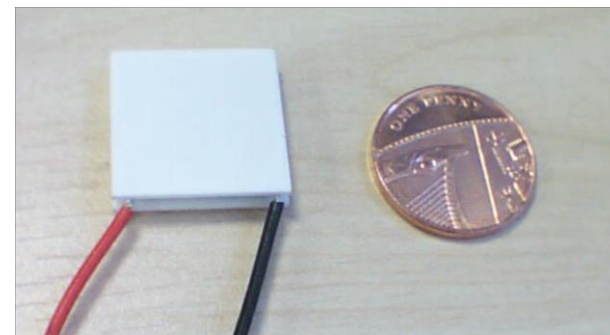


Printed Thermoelectric, Piezoelectric and Pyroelectric Energy Harvesters

Professor Robert Dorey, Chair of Nanomaterials

Introduction

- Harvesting using films
- Creating film harvesters
- Performances

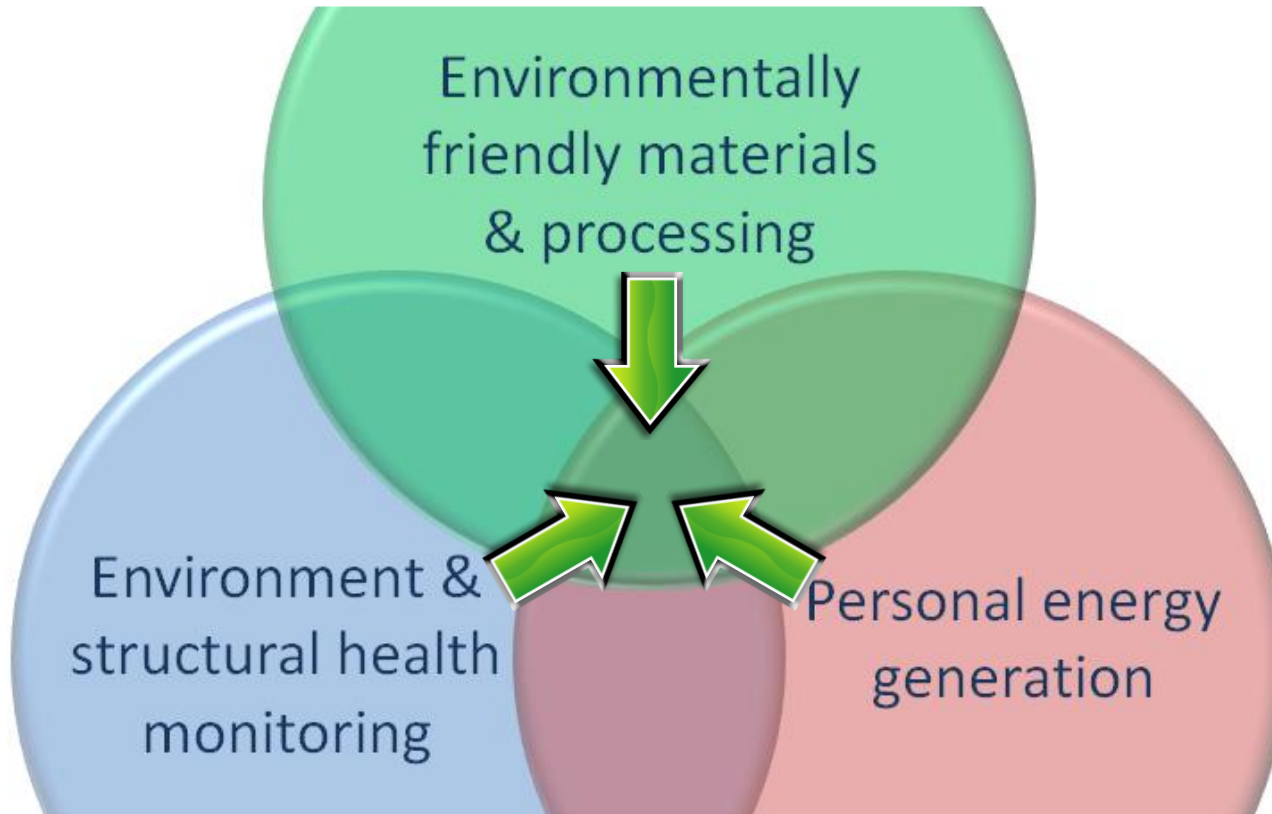


Based on:

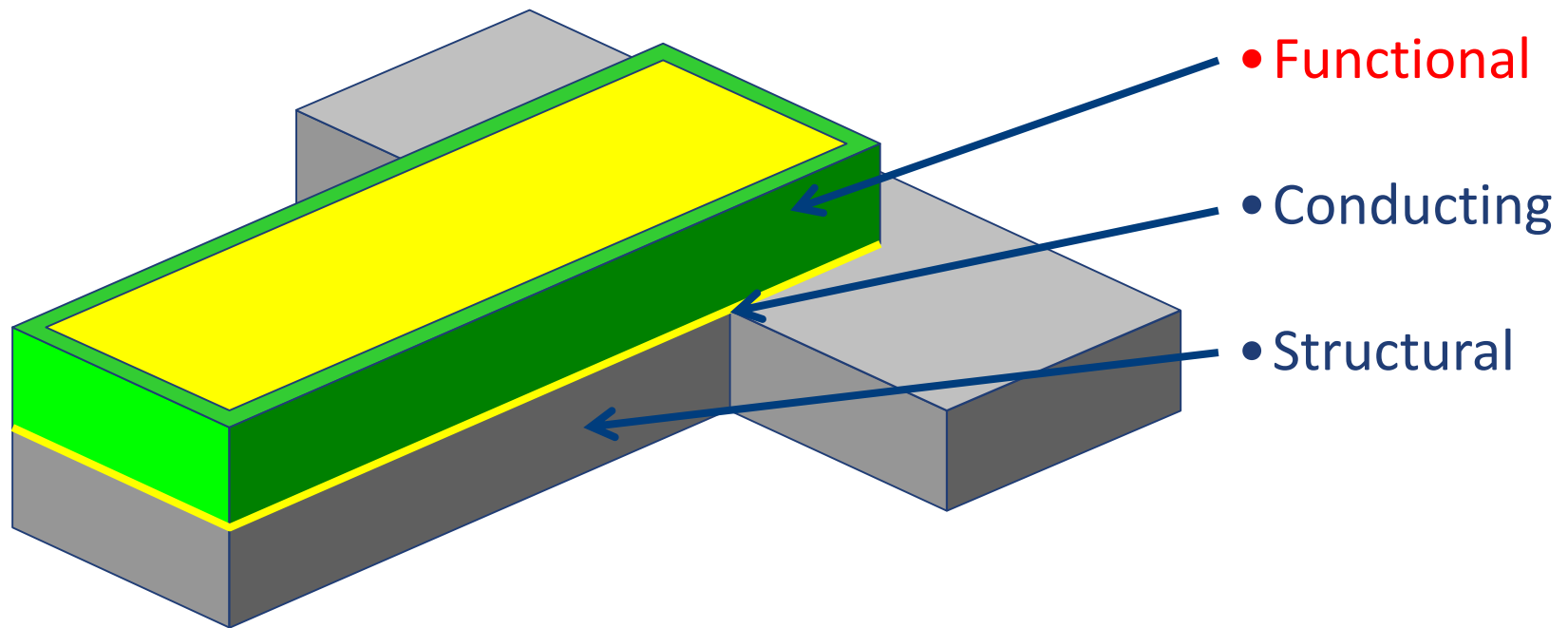
*Integrated Powder-based Thick Films for
Thermoelectric, Pyroelectric and Piezoelectric Energy
Harvesting Devices*

Robert A. Dorey

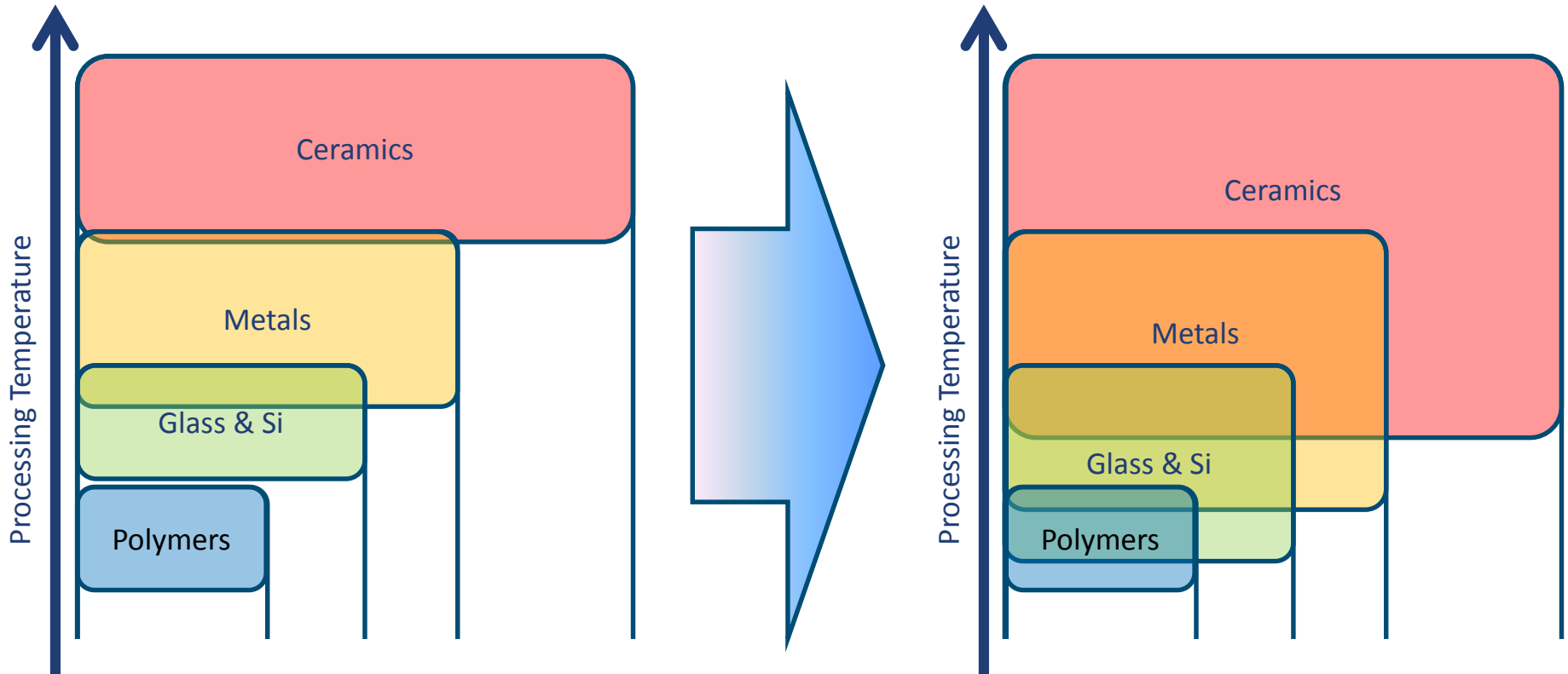
IEEE Sensors Journal, vol 14, no 7, pp 2177-2184, 2014



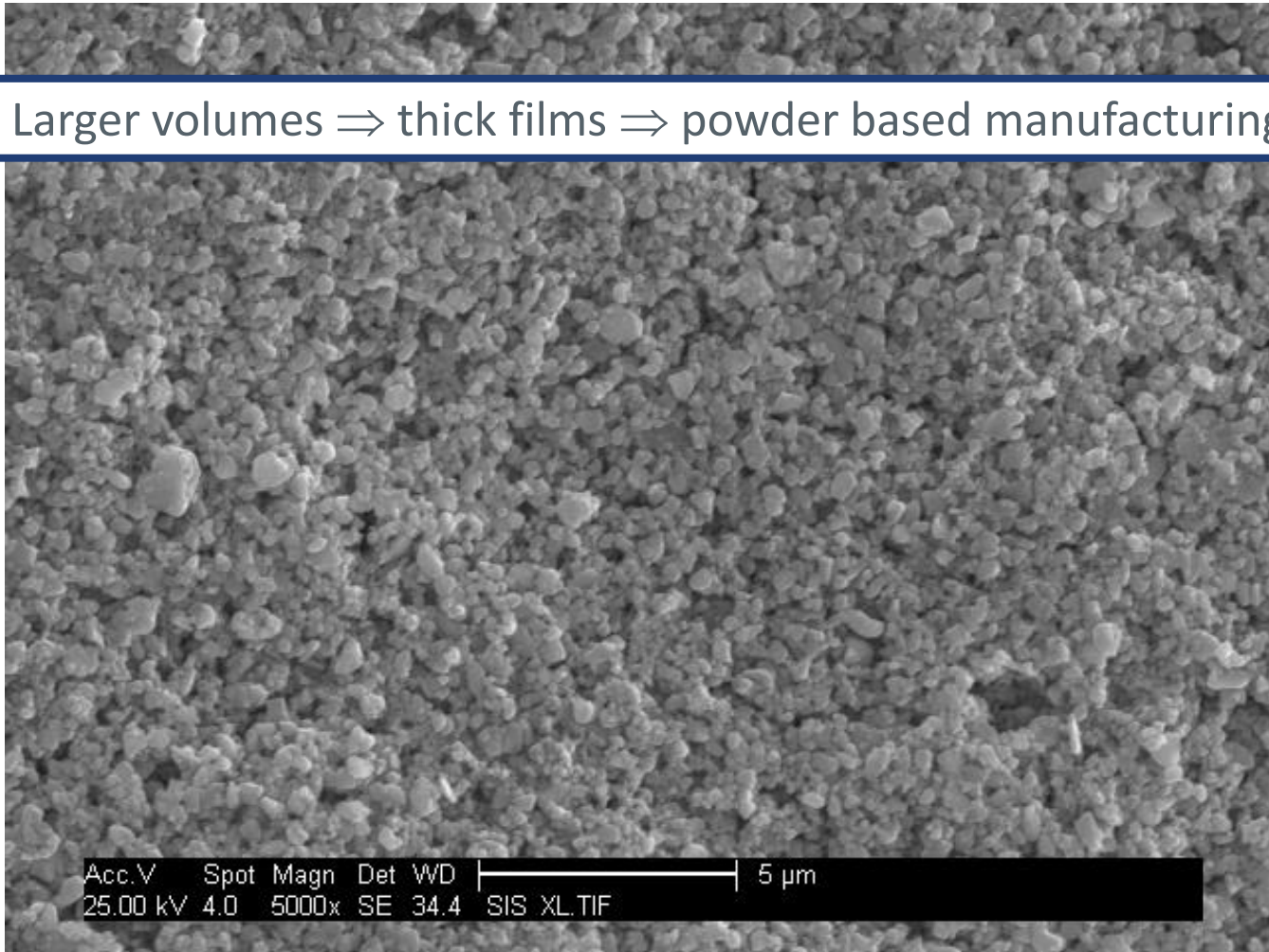
Introduction – ‘typical’ architecture



Co-processing



Power \Rightarrow Larger volumes \Rightarrow thick films \Rightarrow powder based manufacturing



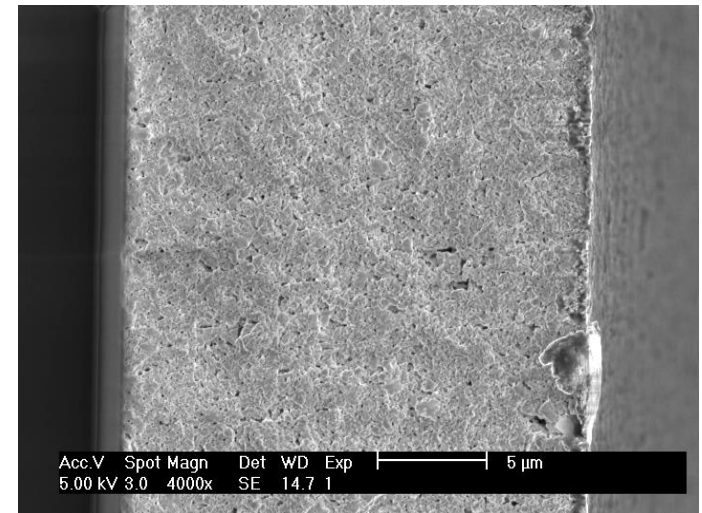
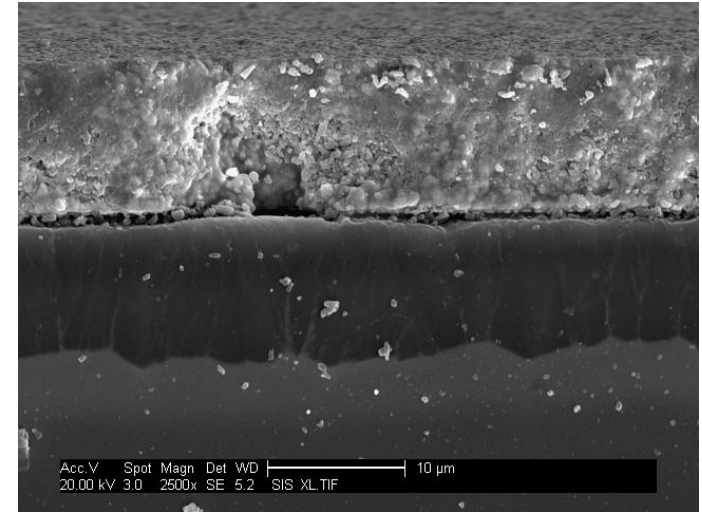
PZT film before sintering

Temperature induced degradation:

- Interdiffusion
- Evaporation
- Degradation

Solutions:

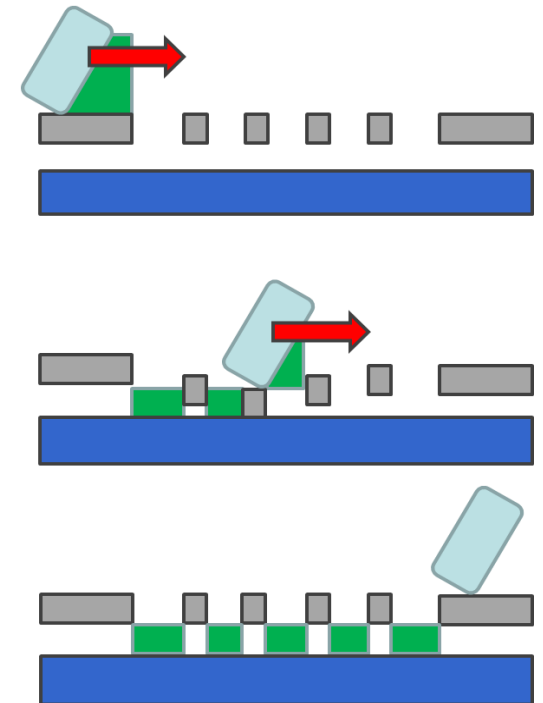
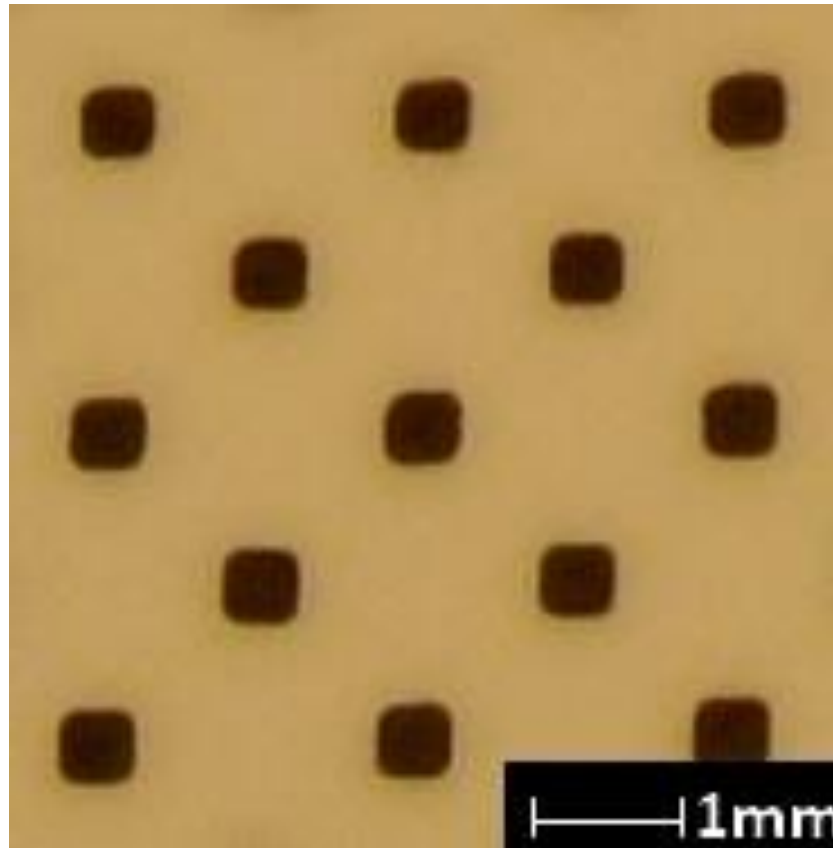
- Low temperature
e.g. $< 750^{\circ}\text{C}$ for PZT/Si
- Diffusion barrier e.g. ZrO_2



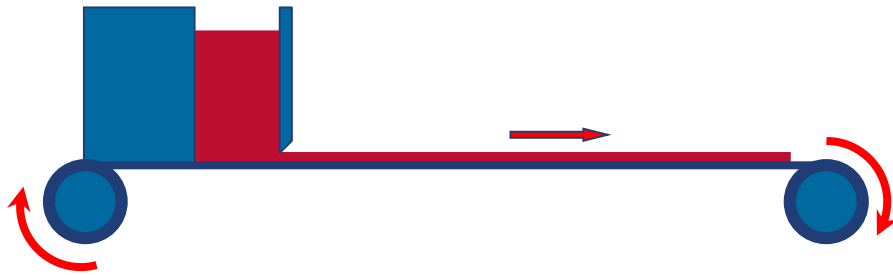
R.A. Dorey, S.B. Stringfellow, R.W. Whatmore, Effect of sintering aid and repeated sol infiltrations on the dielectric and piezoelectric properties of a PZT composite thick film, J.Euro.Ceram.Soc., 22, 2921-2926, 2002.

Manufacturing techniques

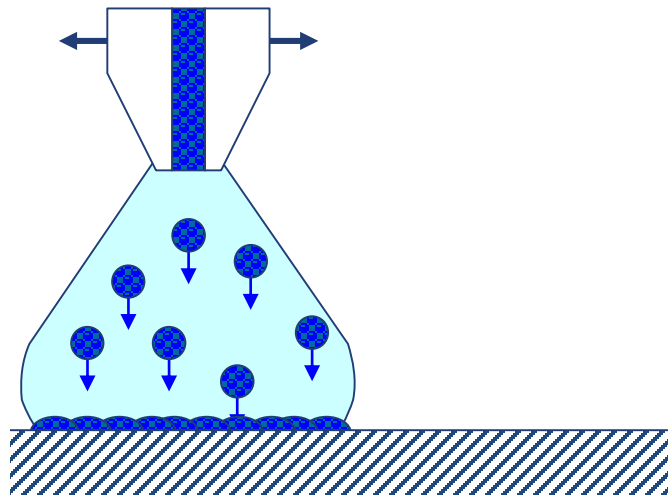
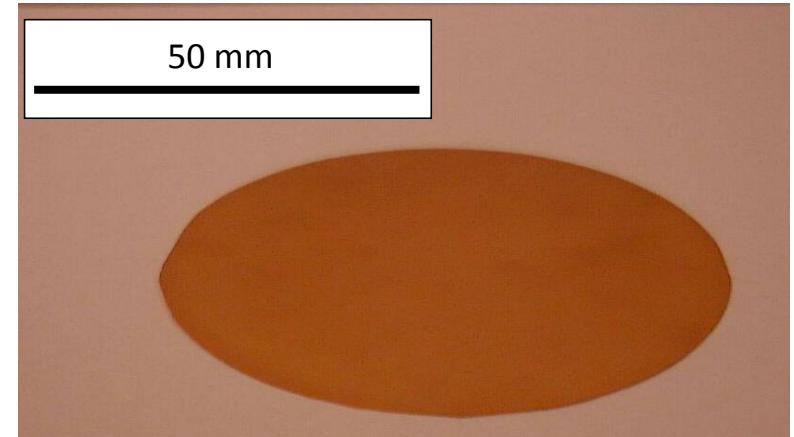
Deposition – screen printing



Deposition – tape casting & spray coating

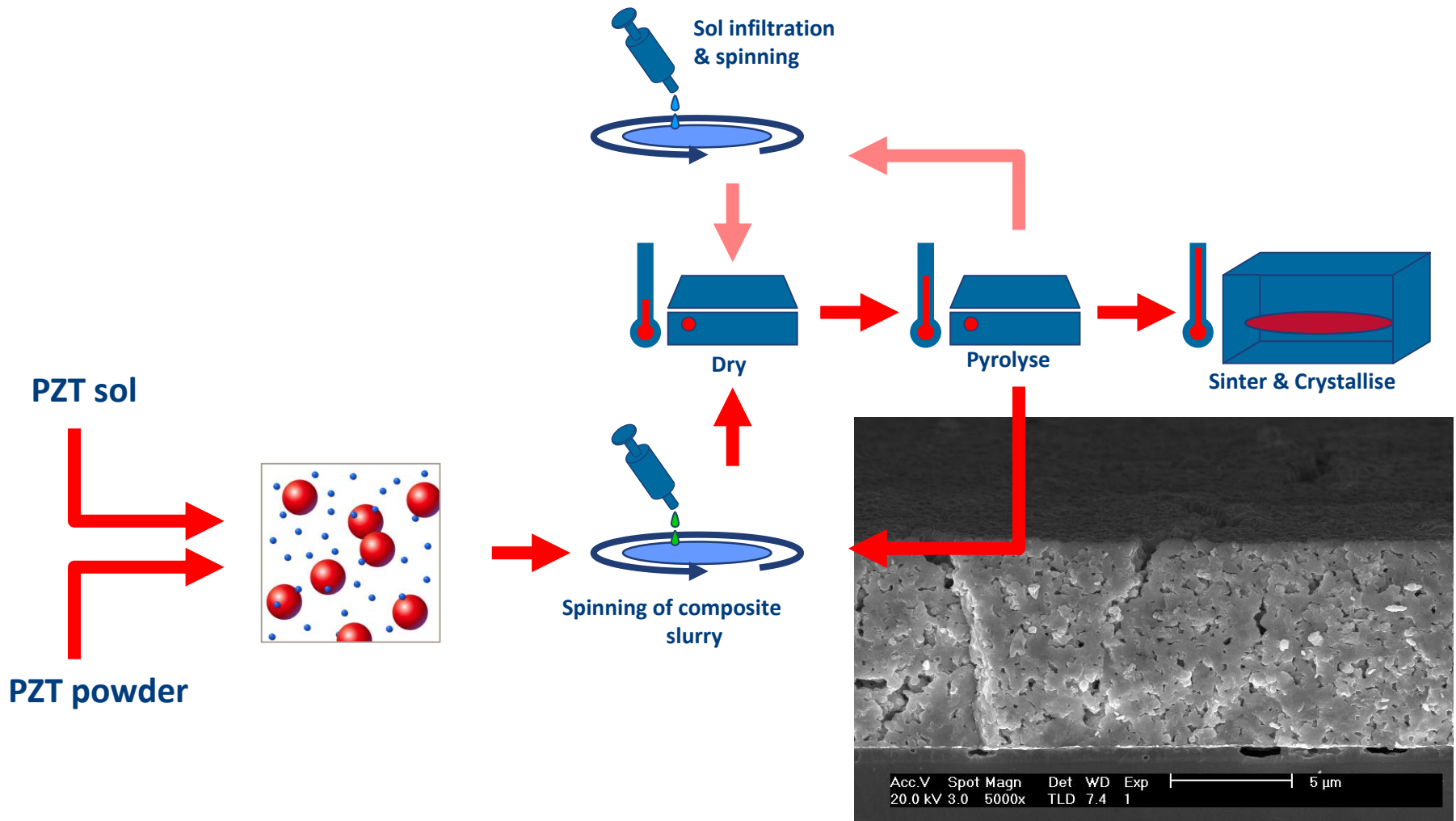


Tape casting

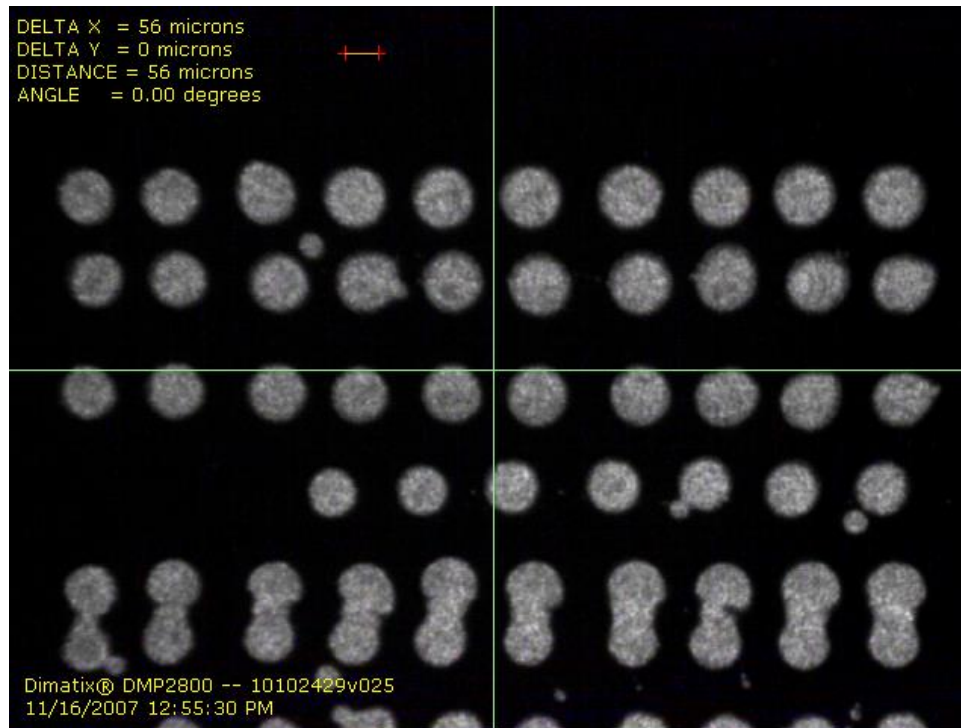


Spray coating

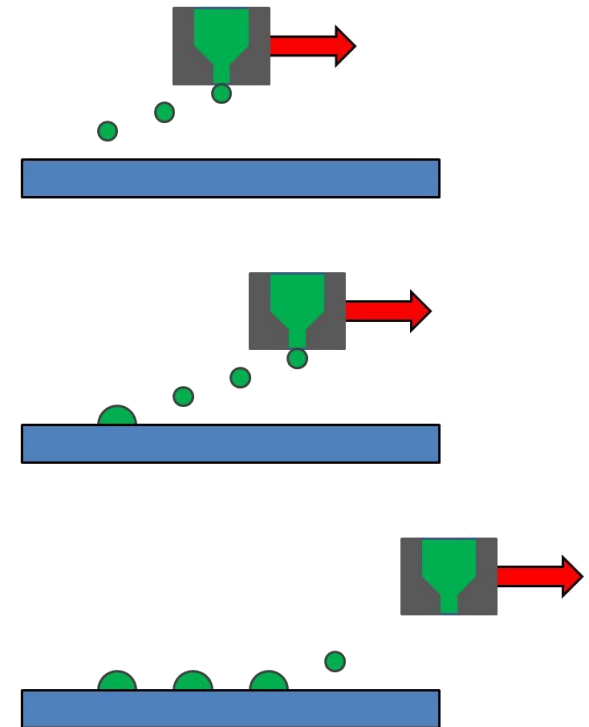
Powder sol gel



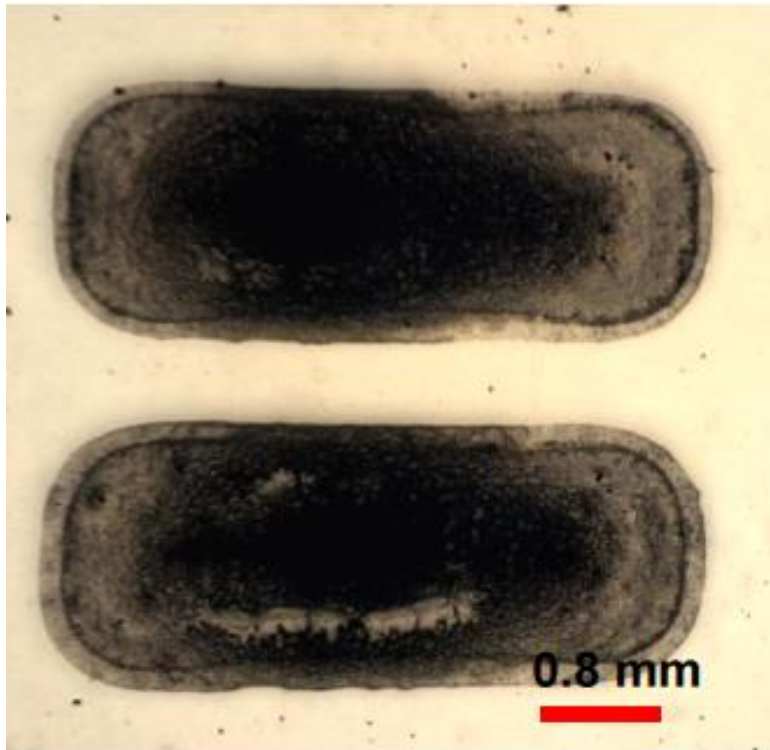
Future manufacturing techniques...



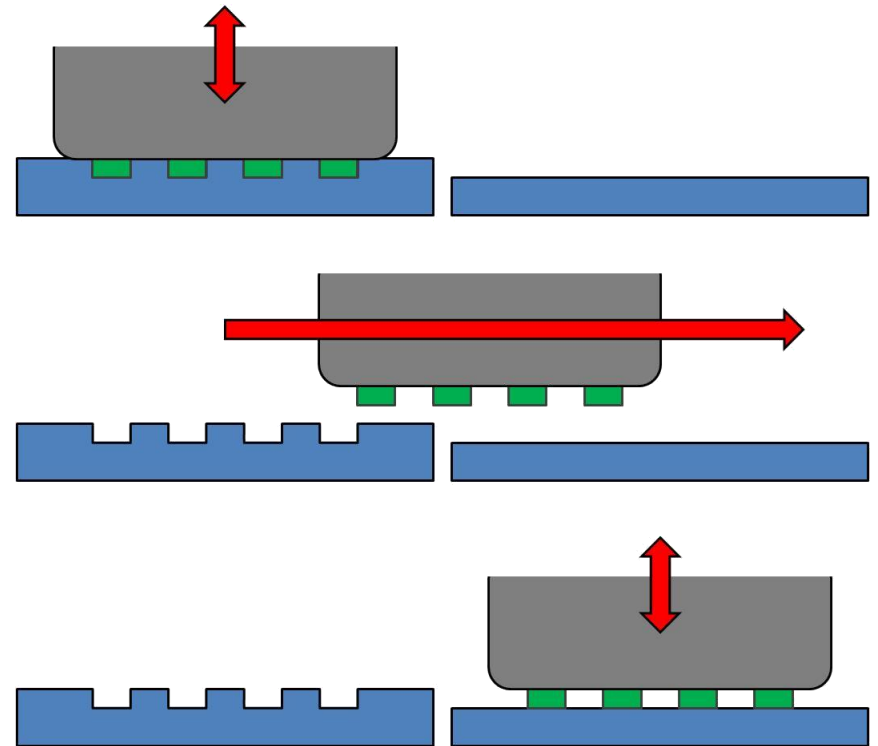
PZT features created by ink jet printing

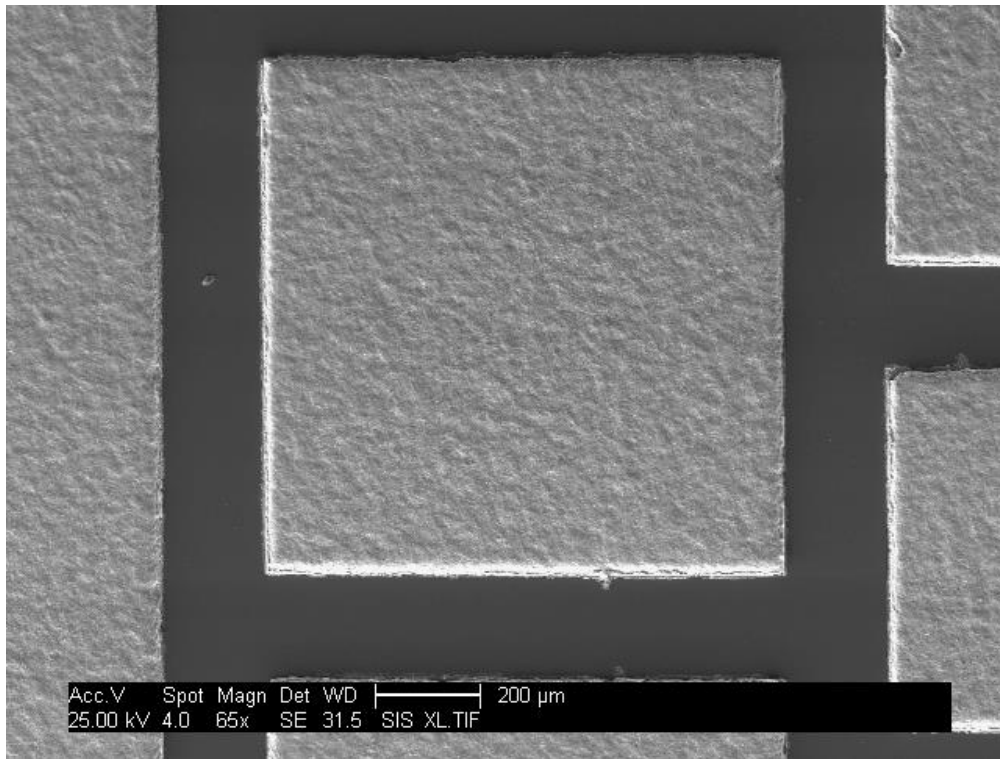


Structuring – pad printing

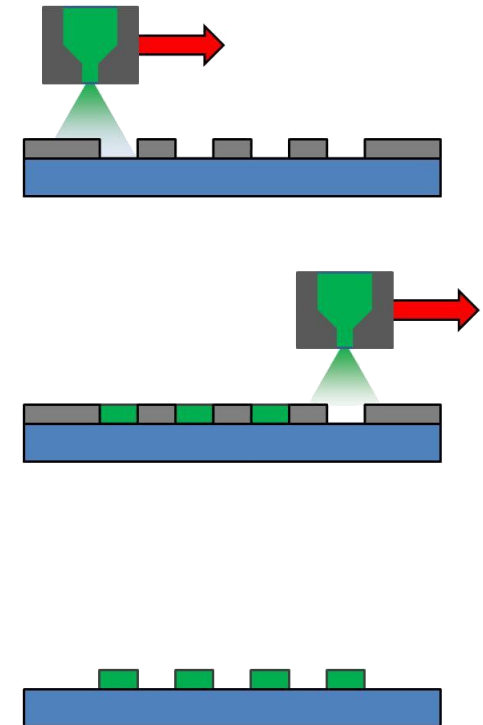


Silver NPs deposited by pad printing

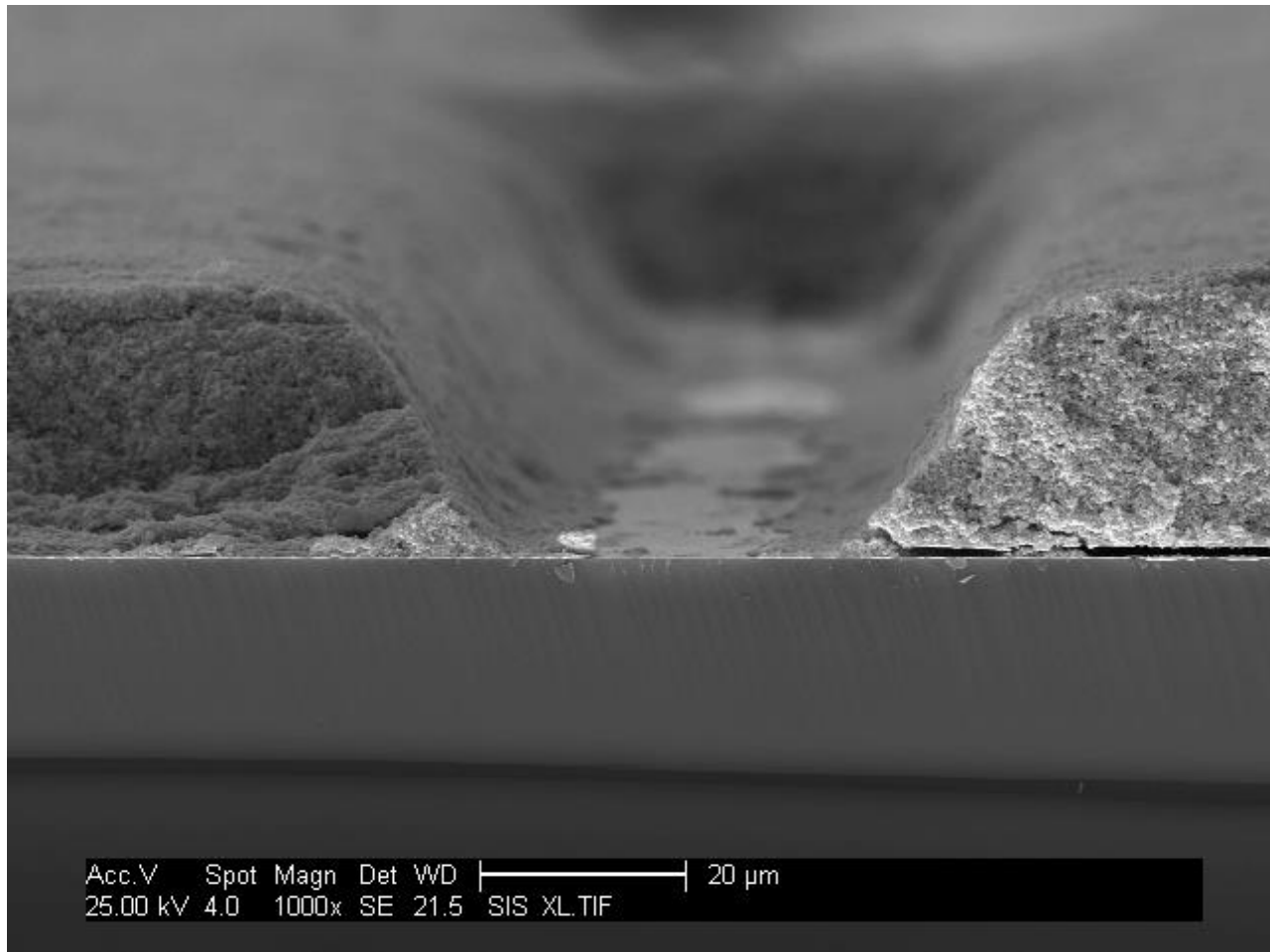




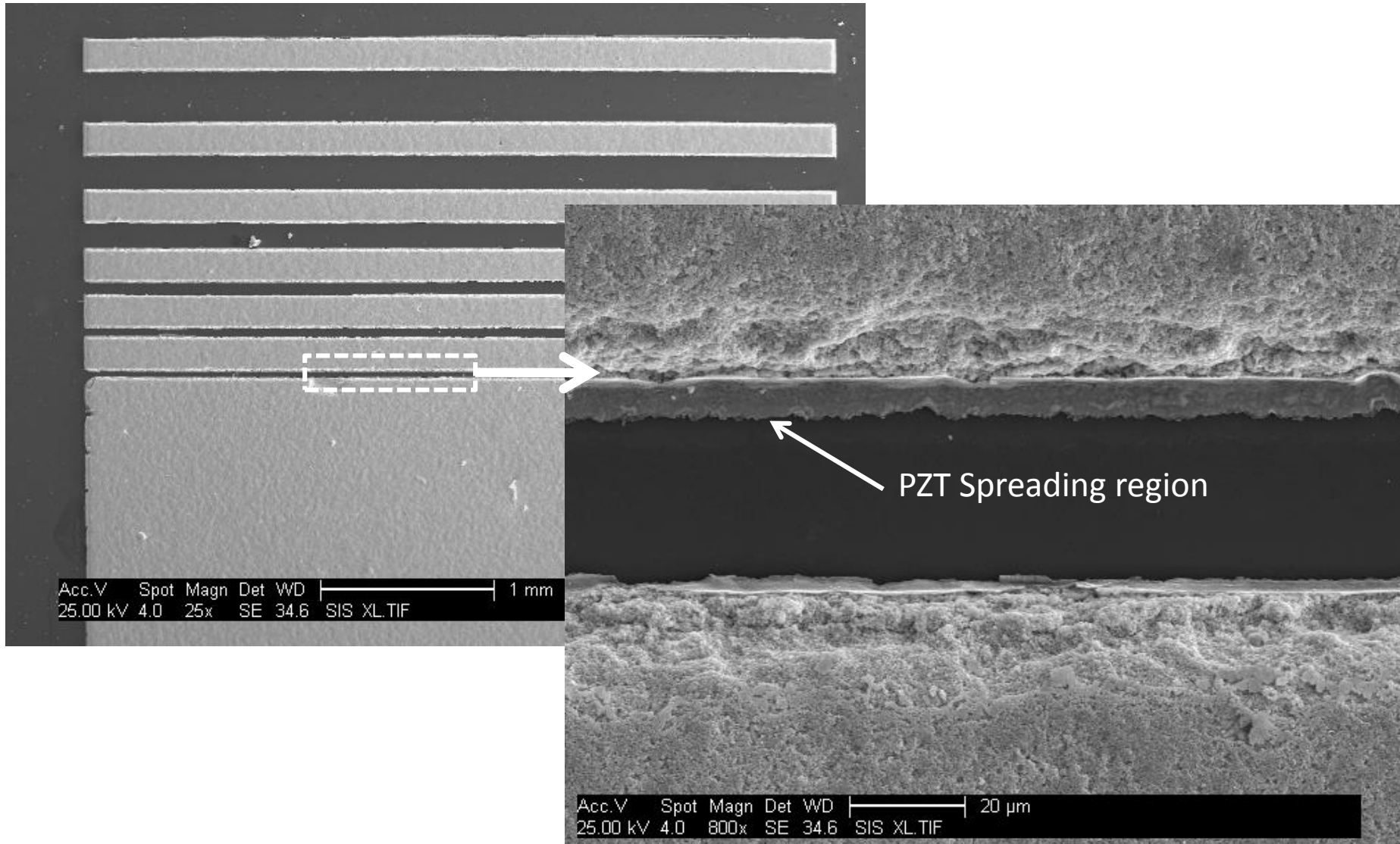
PZT features created by micro moulding



D. Wang, S.A. Rocks, R.A. Dorey, Micromoulding of PZT film structures using electrohydrodynamic atomization mould filling, J.Euro.Ceram.Soc., 29, 1147–1155, 2009. .

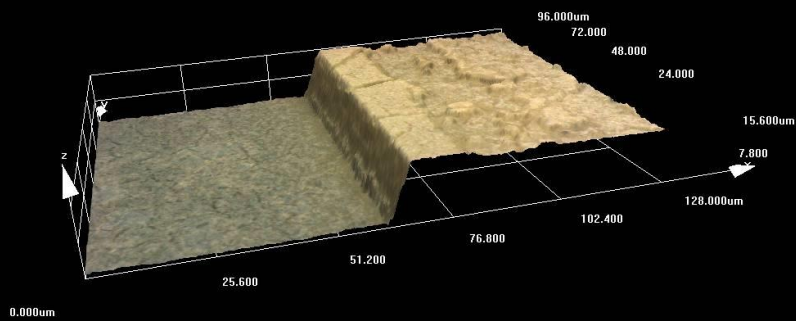


Structuring – micromoulding

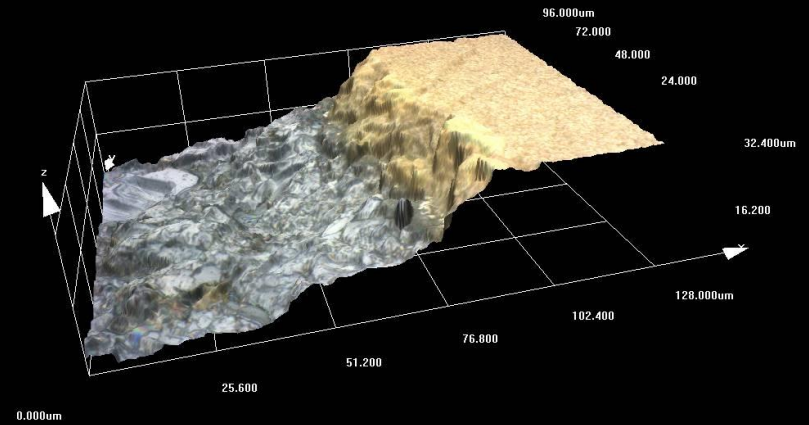


Structuring – additive vs subtractive

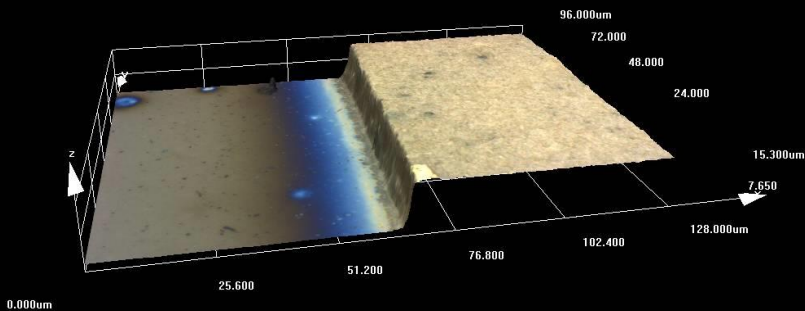
DRIE



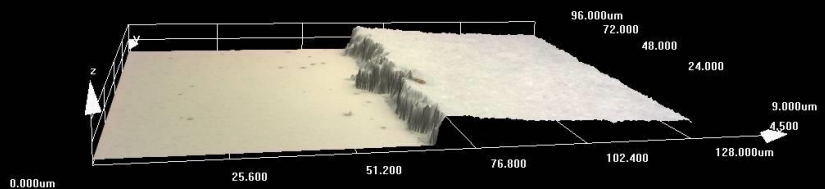
Powder blast



Wet etch



Micromould



Powders, inks & processing temperatures

	Powder Synthesis	Powder	Carrier	Binder	Thickness (μm)	Temperature ($^{\circ}\text{C}$)		
						Drying	Burnout	Sinter
Screen	Mech	76 wt% Bi-Te	22 wt% Toluene	2 wt% Polystyrene	80	60 (hours)	250/10 m	-
Screen	In situ	75 wt% Bi-Te	20.3 wt%	-	-	120/15 m	200/5 m	400/30 m (N_2) 550 (N_2)
Screen	In situ	79.6% ZnSb	18%	None	171	150/10 m	330 $^{\circ}\text{C}$ /20 m	380/20 m (N_2)
Screen	Mech	36-64 vol% Bi-Te	64-36vol% epoxy resin	n/a	100-120	-	-	300 (Ar)
Screen	Calcination	80 wt% PZT	19.2 wt%	0.8 wt%	80-200	150	-	950
Screen	Calcination	PZT	Terpineol	Ethyl cellulose	20-40	120/30 m	550/1 h 700/30 m	900/60 m
Screen	Calcination	PZT	-	-	30	120/10 m	-	925/30 m
Screen	Calcination	PZT	Terpineol & ethyl acetate	PVB-PVAc	22	-	-	800/10 m
Screen	Calcination	Complex perovskites	Terpineol	Ethyl cellulose	24-30	-	-	1000-1250/2 h
Tape	Calcination	PZT	-	PVB	30	vacuum	600/3 h	950-1150
PSG	Calcination	98 wt% PZT	4 wt% sol	None	4	450/3 m	700/10 m	700/15 m
PSG	Calcination	60 wt% PZT	40 wt% sol	None	20	250/60 s	450/15 s	720/20 m
EPD	Calcination	PZT	Acetic acid	None	25	-	-	900 (low O_2)
EPD	Calcination	30 wt% Al_2O_3	ethanol	PVB/PVAc	-	-	-	-

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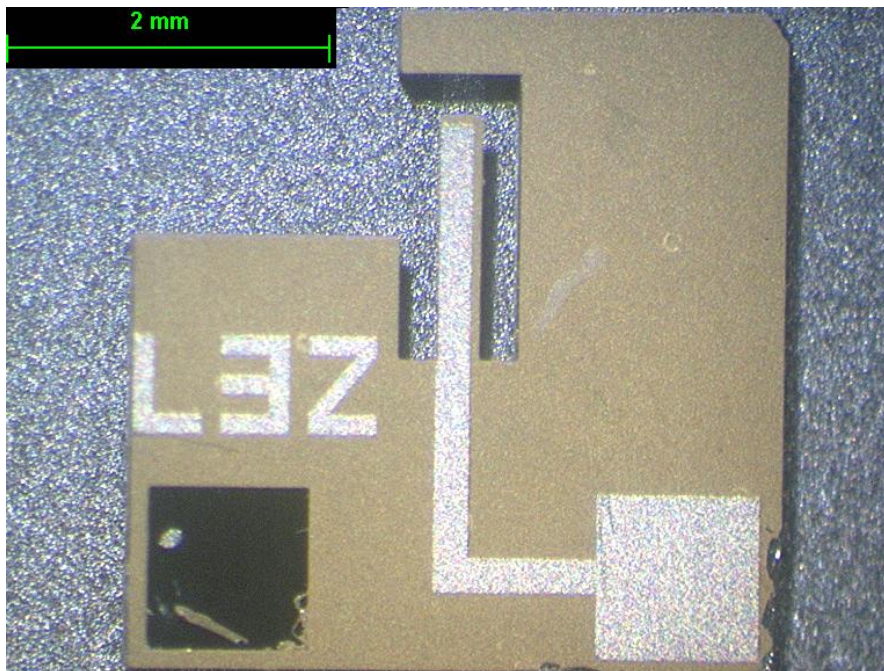
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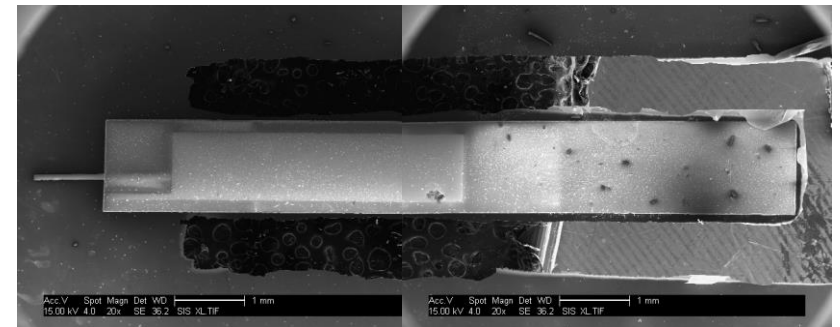
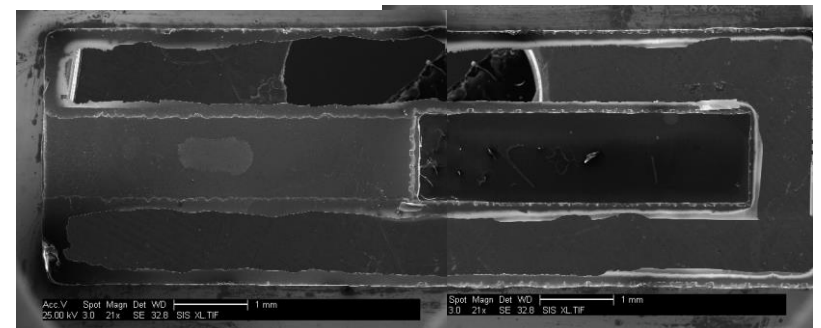
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Piezoelectric energy harvesters



PZT micro energy harvesting cantilever



Performance

Printed piezoelectrics & pyroelectrics

Architecture	Process	Active material thickness (μm)	Substrate thickness (μm)	Dimensions L x W (mm)	Power (μW)	Power density ($\mu\text{W}/\text{cm}^3$)	Operational frequency (Hz)
Bimorph	Screen	20 (x2)	n/a	6.5 x 5.5	33.2 @ 1 g	-	344
Bimorph	Screen	55	none	18 x 9	-	25-33@0.5 g	227
Unimorph	Screen	65 (x2)	250	20 x 8	400	-	230
Unimorph	Screen	22	12.3	(0.38-0.58) x 0.4	-	-	68-154 x 10^3
Unimorph	PSG/spin	4	50	5 x 17	15.4 @ 1 g	97.9 @ 1 g	89
Unimorph	Aerosol	15	20	8 x 6	200 @ 1.5 g	137.5 @ 1.5 g	112
Unimorph	Tape cast	230	250	60 x 30	-	2083	8.2
Pyroelectric	Screen	60-100	500	-	-	-	$\sim 10^{-3}$

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Pyroelectric	Screen	60-100	500	-	-	-	$\sim 10^{-3}$

Likely to be pW level

Printed thermoelectrics

Architecture	Processing	Active material thickness (μm)	Elements	Seebeck coef. ($\mu\text{V}/\text{K}$)	ZT	Power factor ($\alpha^2\sigma$) $\text{mW}/\text{m}^2\text{K}$	Power density ($\mu\text{W}/\text{cm}^3$)
In-plane (n) $(\text{Bi,Sb})_2\text{Te}_3$ (p) $\text{Bi}_2(\text{Se,Te})_3$	Screen	80	5	123	-	0.06	-
In-plane (unimat) Bi_2Te_3	Dispenser	120	62	200 @ RT	0.31	0.27	130 (20 K ΔT)
Film only Bi_2Te_3	Screen	80	-	140	0.61 (@RT)	2.1	-
Film only $\text{Ca}_3\text{Co}_4\text{O}_9$	Aerosol	55	-	150-170 (@300-700°C)	-	-	-
Film only ZnSb	Screen	-	-	355-365 (@ 330-480K)			
$\text{Bi}_{0.85}\text{Sb}_{0.15}/\text{epoxy}$	Screen			97			
Ag-Ni	Screen			22-25 @RT		0.6-1.1 @ ~RT	30 (200 K ΔT)
Multilayer (n) LaSrTiO_3 (p) Ni-Mo	Multilayer	(n) 100 (p) 25	50	(n) 20 @ RT (p) 153 @ RT	(n) 0.32 @623K (p) 0.04 @623K		450 (360 K ΔT)
In-plane (n) Bi_2Te_3 (p) Sb_2Te_3	Co-evaporation	-	8	(n) 248 (p) 188	(n) 0.93 @ 300K (p) 0.26 @ 300K	(n) 4.87 @ 300K (p) 2.81 @ 300K	-
Π Cu/Ni	Electro-plate	150	51	20.6	-	-	0.012 (0.12 K ΔT)

Summary

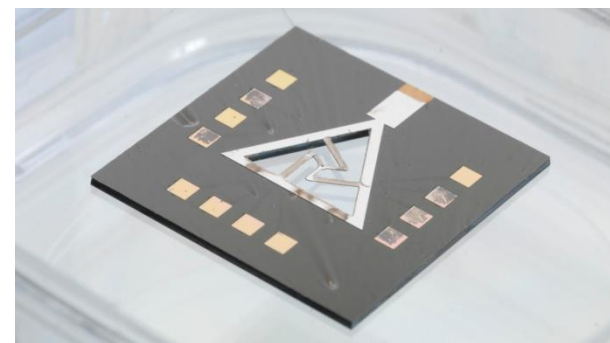
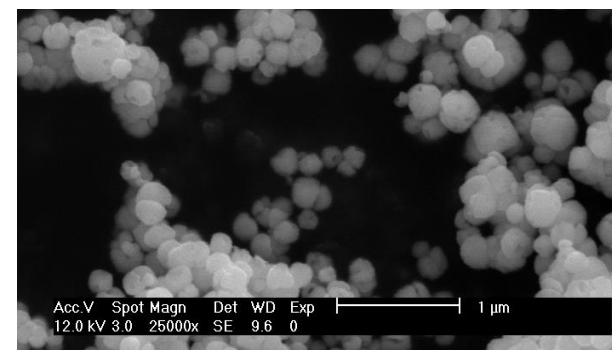
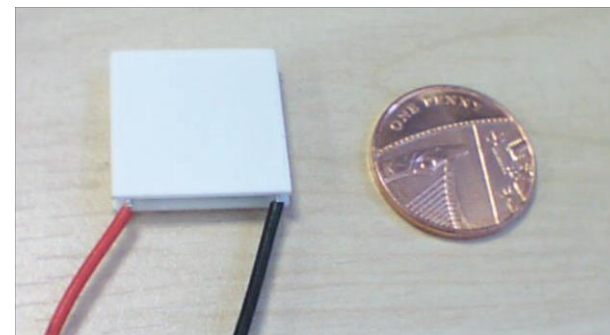
- Film based harvesters can be fabricated
- Thick films are reliant on consolidation of powders
i.e. heat required
- Film forming techniques are continually improving
- Cheaper & quicker to fabricate than bulk systems

Based on:

*Integrated Powder-based Thick Films for
Thermoelectric, Pyroelectric and Piezoelectric Energy
Harvesting Devices*

Robert A. Dorey

IEEE Sensors Journal, vol 14, no 7, pp 2177-2184, 2014



Contact details

Professor Robert Dorey

Chair in Nanomaterials

Department of Mechanical Engineering Sciences,

Faculty of Engineering and Physical Sciences,

University of Surrey

Guildford

Surrey

UK

GU2 7XH

r.dorey@surrey.ac.uk

www.twitter.com/Robert_Dorey

www.surrey.ac.uk

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